



Customer Information Notification

2015090171

Issue Date: 26-Sep-2015
Effective Date: 09-Jan-2016

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QUALITY

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input type="checkbox"/> Assembly Materials	<input checked="" type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

BUK9675-100A & BUK9575-100A datasheet revision

Information Notification

The BUK9675-100A & BUK9575-100A datasheets have been updated to reflect the latest typical device performance. Changes have been made in the datasheets as follows

- . Typical dynamic characteristics in the characteristics table have been updated (Trr -> 53.7ns, Qrr -> 126nC)
- . Typical characteristic graphs - output characteristic (Figure 6)
- . Typical characteristic graphs - gate charge, capacitance, diode characteristics (Figures 15,16,17)
- . A gate charge waveform definition graph has been included (Figure 14)
- . Add typical values for QG(tot), QGS and QGD.
- . The avalanche current conditions have been changed from 14.2A to 23A as per latest NXP design rules
- . Footnotes have been added to the avalanche energy table:
Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.
Refer to application note AN10273 for further information.
- . Update the continuous drain current graph (Figure 2) from percentage to absolute maximum values
- . Update the avalanche rating figure (Figure 4)

Why do we issue this Information Notification

The change is being made to ensure that the datasheet, product and spice models are all aligned

Identification of Affected Products

Product identification does not change

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

N/A

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

e-mail address powermos.pcn@nxp.com

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NXP Quality Management Team.

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